Exhibit R-2, RDT&E Budget Item Justification: PB 2014 Office of Secretary Of Defense

R-1 ITEM NOMENCLATURE

0400: Research, Development, Test & Evaluation, Defense-Wide

PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program

DATE: April 2013

BA 3: Advanced Technology Development (ATD)

APPROPRIATION/BUDGET ACTIVITY

		•										
COST (\$ in Millions)	All Prior Years	FY 2012	FY 2013 [#]	FY 2014 Base	FY 2014 OCO ##	FY 2014 Total	FY 2015	FY 2016	FY 2017	FY 2018	Cost To Complete	Total Cost
Total Program Element	-	49.026	21.966	34.041	-	34.041	22.539	23.268	23.574	24.031	Continuing	Continuing
P680: Manufacturing Science and Technology Program	-	49.026	21.966	34.041	-	34.041	22.539	23.268	23.574	24.031	Continuing	Continuing

^{*} FY 2013 Program is from the FY 2013 President's Budget, submitted February 2012

A. Mission Description and Budget Item Justification

Defense-wide Manufacturing Science and Technology (DMS&T), established within the Manufacturing Technology Program directed in Title 10 USC Section 2521, provides the Department with a comprehensive manufacturing program to achieve the strategic goals of focused technology, improved acquisition across the life cycles, and cost-effective logistics. By designing for manufacturability early in development, anticipated results will have an impact on increasing reliability and decreasing the life cycle burden of weapon systems. The mission to anticipate and close gaps in defense manufacturing capabilities and drive significant system life cycle affordability benefits makes DMS&T an increasingly important leveraging tool in the current budget environment.

DMS&T will: 1) address manufacturing enterprise game-changing initiatives that are beyond the scope of any one Military Department or Defense Agency or platform and, 2) establish and mature cross-cutting manufacturing processes required for transitioning emerging technologies which impact the time lines, affordability, and productivity of acquisition programs and shorten the deployment cycle times.

The DMS&T program is fundamental to a coordinated development process. Concurrent development of manufacturing processes with the S&T development enables the use of emerging technologies. Key technical areas for investment for DMS&T include Advanced Electronics and Optics Manufacturing, Advanced Materials Manufacturing, and Enterprise and Emerging Manufacturing. Advanced Electronics and Optics addresses advanced manufacturing technologies for a wide range of applications such as sensors, radars, power generation, switches, and optics for defense applications. Advanced Materials addresses advanced manufacturing technologies for a wide range of materials such as composites, metals, ceramics, nanomaterials, metamaterials, and low observables. Enterprise and Emerging Manufacturing addresses advanced manufacturing technologies and enterprise business practices for defense applications. Key focus areas include the industrial information infrastructure, advanced design/qualification/cost tools, supply network integration technologies and management practices, direct digital (or additive) manufacturing, machining; robotics, assembly, and joining.

PE 0603680D8Z: Defense Wide Manufacturing Science and Technology ...

^{##} The FY 2014 OCO Request will be submitted at a later date

Exhibit R-2, RDT&E Budget Item Justification: PB 2014 Office of Secretary Of Defense DATE: April 2013

EV 2042

APPROPRIATION/BUDGET ACTIVITY

R-1 ITEM NOMENCLATURE

0400: Research, Development, Test & Evaluation, Defense-Wide

PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program

EV 2044 OCO

EV 2044 Tatal

EV 2044 Bass

BA 3: Advanced Technology Development (ATD)

B. Program Change Summary (\$ in Millions)	FY 2012	FY 2013	FY 2014 Base	FY 2014 OCO	FY 2014 Total
Previous President's Budget	46.277	21.966	22.407	-	22.407
Current President's Budget	49.026	21.966	34.041	-	34.041
Total Adjustments	2.749	0.000	11.634	-	11.634
 Congressional General Reductions 	-	-			
 Congressional Directed Reductions 	-	-			
 Congressional Rescissions 	-	-			
 Congressional Adds 	-	-			
 Congressional Directed Transfers 	-	-			
 Reprogrammings 	2.749	-			
SBIR/STTR Transfer	-	-			
 AT&L More Disciplined Use of Resources 	-	-	-0.366	-	-0.366
- two percent reduction for resource					
realignment					
 Establishment of collaborative Institutes for 	-	-	12.000	-	12.000
Manufacturing Innovation per Administration/					
OMB guidance					

Congressional Add Details (\$ in Millions, and Includes General Reductions)

Project: P680: Manufacturing Science and Technology Program

Congressional Add: Industrial Base Innovation Fund

	FY 2012	FY 2013
	30.000	-
Congressional Add Subtotals for Project: P680	30.000	0.000
Congressional Add Totals for all Projects	30.000	0.000

Change Summary Explanation

FY 2012 \$3.000 approved omnibus reprogramming per FY12-18 PA to support emerging manufacturing projects to continue significant advancements to additive manufacturing processes.

FY 2014 includes \$12.000 for Advanced Manufacturing Innovation Institute program priorities of the Department and the Administration.

PE 0603680D8Z: Defense Wide Manufacturing Science and Technology ... Office of Secretary Of Defense

UNCLASSIFIED Page 2 of 19

R-1 Line #47

Exhibit R-2A, RDT&E Project Ju	ustification	: PB 2014 C	Office of Sec	cretary Of D)efense					DATE: Ap	ril 2013		
APPROPRIATION/BUDGET ACT					111211111111111111111111111111111111111				PROJECT	-			
0400: Research, Development, Te	0400: Research, Development, Test & Evaluation, Defense-Wide				PE 0603680D8Z: Defense Wide P680				P680: <i>Man</i>	: Manufacturing Science and			
BA 3: Advanced Technology Development (ATD)				Manufacturing Science and Technology Tech			Technolog	chnology Program					
	, ,	,			Program	J		0,		J			
COST (\$ in Millions)	All Prior Years	FY 2012	FY 2013 [#]	FY 2014 Base	FY 2014 OCO ##	FY 2014	FY 2015	FY 2016	FY 2017	FY 2018	Cost To	Total	
	rears	F1 2012	F1 2013	Dase	000	Total	F1 2015	F1 2016	F1 2017	F1 2010	Complete	Cost	
P680: Manufacturing Science and Technology Program	-	49.026	21.966	34.041	-	34.041	22.539	23.268	23.574	24.031	Continuing	Continuing	

[#] FY 2013 Program is from the FY 2013 President's Budget, submitted February 2012

A. Mission Description and Budget Item Justification

The DMS&T program has a two-pronged approach: 1) technology initiatives and 2) specific single projects. Technology initiatives, in collaboration with the Joint Defense Manufacturing Technology Panel (JDMTP) and industry, identify and develop investment strategies to advance the manufacturing processes needed to support the specific technology. Above-the-shop-floor investments focus on new manufacturing processes that have potential to significantly improve manufacturing efficiencies. Single specific projects address investment opportunities not associated with selected technology initiatives and enable the program to respond to urgent, compelling manufacturing needs and provide seed funding to more high risk-high payoff technologies.

Data calls are launched through two methods to identify technology initiatives and single specific issues requiring investment. One method is through the JDMTP. The JDMTP is comprised of the ManTech Directors from the Services, Defense Logistics Agency, and Office of Secretary of Defense (OSD). The call is distributed through the ManTech Directors to the four JDMTP sub panels: Metals Processing and Fabrication Subpanel, Composites Processing and Fabrication Subpanel, Electronics Processing and Fabrication Subpanel and Advanced Manufacturing Enterprise Subpanel. Potential candidates are evaluated by the JDMTP based on criteria set forth in the call and announcements and down-selected for further development prior to final selection. The other method is through Broad Agency Announcements to industry. Priority is given to investments that support affordability and producibility of critical enabling manufacturing technologies that cut across multiple platforms. Investments also balance defense priorities in specialty materials, electronics, propulsion and power, and manufacturing processes including "above the shop floor" (lean and business technologies facilitating interoperable manufacturing). Final projects are selected by the OSD ManTech Director, considering input from the JDMTP and Director of Manufacturing, and as approved by Deputy Assistant Secretary of Defense, Manufacturing and Industrial Base Policy (MIBP). Technology initiatives and projects are executed at the Component level.

B. Accomplishments/Planned Programs (\$ in Millions)	FY 2012	FY 2013	FY 2014
Title: Advanced Electronics Manufacturing - Advanced RF Packaging	2.375	1.875	0.000
Description: This effort applies an existing radar system already in production to satisfy a low-cost, open-architecture radar requirement for the Littoral Combat Ship (LCS) program. This program will reduce the cost of the current radar system by \$1M per ship set, and will fit into the existing TRS-3D top side and below decks available footprint. The open architecture configuration will allow upgrades for new technologies over the lifetime of the program as well as offer lower cost via the potential for open competition for the radar's building blocks. Radar manufacturing and support capability will be transferred from a foreign company to a domestic company and facility. Transmit/Receive (T/R) module packaging cost will be reduced through near-			

PE 0603680D8Z: Defense Wide Manufacturing Science and Technology ...

Office of Secretary Of Defense

^{##} The FY 2014 OCO Request will be submitted at a later date

	UNCLASSIFIED				
Exhibit R-2A, RDT&E Project Justification: PB 2014 Office of Secreta	ary Of Defense		DATE:	April 2013	
APPROPRIATION/BUDGET ACTIVITY 0400: Research, Development, Test & Evaluation, Defense-Wide BA 3: Advanced Technology Development (ATD)	R-1 ITEM NOMENCLATURE PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program	P680: <i>M</i> 8	PROJECT P680: Manufacturir Technology Progra		nd
B. Accomplishments/Planned Programs (\$ in Millions) hermetic, commercial Monolithic Microwave Integrated Circuit (MMIC) p (SMT) assembly techniques, reducing touch labor costs. Model Based supportability and technology refresh via an Intelligent Technical Data P components as a part of this program will have a direct impact on the Vo \$1M/hull cost savings for the Navy. This effort will provide the Navy with be able to accommodate different Monolithic Microwave Integrated Circuitechnologies, processor, and power supplies from multiple vendors. The equipment (antenna) with the below-deck equipment (signal processing below-deck equipment (allowing a lower center of gravity and thus impro	Enterprise (MBE) concepts will be integrated to enseakage. The commercial packaging effort for T/R colume Search Radar (VSR) on CVN-79 – creating as the first truly open architecture radar solution that uit (MMIC) technologies, Line Replaceable Unit (LF e system will use fiber optics to connect the above and control) which will allow greater flexibility in local	gy sure module a : will RU) -deck	Y 2012	FY 2013	FY 2014
FY 2012 Accomplishments: The project contract began in November 2011 and the Transition Plan w Technical Data Package (TDP) related software and hardware was rece	•				

The project contract began in November 2011 and the Transition Plan was signed by all stakeholders in December 2011. All Technical Data Package (TDP) related software and hardware was received, installed and is functional. A complete drawing package for the TDP was received. Requirements Traceability Matrix and Rational DOORS data was received. Development of the S-band Open-architecture Component Knowledge and Event Tester (SOCKET) LRU based verification system is in progress. The SOCKET test equipment was specified and ordered. The SOCKET system requirements definition was completed. The SOCKET Kernel is under configuration management and revision control via a WindChill environment. The SOCKET Preliminary Design Review was completed. Supplier evaluation for the design and production of the PowerBook Transmit/Receive (T/R) module was completed. The decision was made to re-design the PowerBook in house, leveraging the existing design, and making use of Advanced RF Packaging and Automated Assembly ManTech improvements.

FY 2013 Plans:

Develop the S-band Open-architecture Component Knowledge and Event Tester (SOCKET) Graphical User Interface (GUI), interface to test equipment, Intelligent Technical Data Package (ITDP) interface, data logging & LRU test scripts, and training & simulator software. Complete the SOCKET Critical Design Review. Complete SOCKET integration and testing, and a SOCKET string test. Write SOCKET test reports and the user manual. Complete the SOCKET LRU based verification system and deliver the SOCKET hardware and software to the Navy.

Complete gallium nitride (GaN) component supplier evaluation and selection for the Transmit/Receive (T/R) module. Complete PowerBook T/R module Preliminary Design Review (PDR), Critical Design Review (CDR). Build, test, and qualify the PowerBook module. Conduct System Engineering training. Complete land-based radar integration and testing. Initiate the sub-array string testing. Complete the String Test Verification Demonstration. Deliver the final Intelligent Technical Data Package (ITDP).

PE 0603680D8Z: Defense Wide Manufacturing Science and

Technology ...

Office of Secretary Of Defense

R-1 Line #47

ry Of Defense		DATE: /	April 2013	
R-1 ITEM NOMENCLATURE PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program	P680: <i>Ma</i>	nufacturir	•	nd
S manufacturer to the domestic manufacturer. Con		Y 2012	FY 2013	FY 2014
		4 394	4 000	0.000
is) is unavailable. The size, weight, power, and cost cations. Chip Scale Atomic Clock (CSAC) provides in time accuracy. The focus of this project is leveraging the CSAC technology to reduce operational costs es include improving the existing batch manufacturing mbly, and sub-system testing to reduce the "touch homology to foster competition and ensure a visual session can produce CSAC in small quantities with low ity at an affordable cost (\$100-\$300/unit). Successful SR systems, regardless of the presence or absent	ng ours" viable ul ce of			0.000
sics package redesign implies a manufacturing rate of	of			
nproved physics package design and yield engineer embly run rate, validate the cost model. Achieve an facturing Readiness Level (MRL)8. Deliver Phase II	ing. end-			
T established (mean	R-1 ITEM NOMENCLATURE PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program S manufacturer to the domestic manufacturer. Condence, Surveillance, and Reconnaissance (C4ISR) sy is unavailable. The size, weight, power, and cost cations. Chip Scale Atomic Clock (CSAC) provides in time accuracy. The focus of this project is leveraging the CSAC technology to reduce operational costs are include improving the existing batch manufacturing mbly, and sub-system testing to reduce the "touch include vendors to foster competition and ensure a visual state of the condence CSAC in small quantities with low the sesting the cost (\$100–\$300/unit). Successful states an affordable cost (\$100–\$300/unit). Successful stary code in a hostile Electro Magnetic Interference in the code in a hostile Electro Magnetic Interference in the code i	R-1 ITEM NOMENCLATURE PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program FS manufacturer to the domestic manufacturer. Complete Ince, Surveillance, and Reconnaissance (C4ISR) systems Is unavailable. The size, weight, power, and cost rations. Chip Scale Atomic Clock (CSAC) provides In time accuracy. The focus of this project is leveraging the CSAC technology to reduce operational costs resinclude improving the existing batch manufacturing mbly, and sub-system testing to reduce the "touch hours" nultiple vendors to foster competition and ensure a viable rese can produce CSAC in small quantities with low that an affordable cost (\$100-\$300/unit). Successful AISR systems, regardless of the presence or absence of litary code in a hostile Electro Magnetic Interference (EMI) Enabled physics package tester. Reduced electronics respectively and the provided Explosive reproved physics package design and yield engineering. The provided Explosive reproved physics package design and yield engineering.	R-1 ITEM NOMENCLATURE PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program FY 2012 FY 201	R-1 ITEM NOMENCLATURE PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program FY 2012 FY 2013 FY 2013 FY 2013 FY 2013 FY 2013 FY 2014 FY 2015 FY 2015 FY 2015 FY 2016 FY 2016 FY 2016 FY 2017 FY 2017 FY 2018 FY 2018 FY 2018 FY 2019 FY 2019

Exhibit R-2A, RDT&E Project Justification: PB 2014 Office of Secreta	ry Of Defense	,	DATE:	April 2013	
APPROPRIATION/BUDGET ACTIVITY 0400: Research, Development, Test & Evaluation, Defense-Wide BA 3: Advanced Technology Development (ATD)	R-1 ITEM NOMENCLATURE PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program		Manufacturing Science and nology Program		nd
B. Accomplishments/Planned Programs (\$ in Millions)			FY 2012	FY 2013	FY 2014
Achieve Low Rate Initial Production (LRIP) readiness. Realize final production other programs of record.	uction capability goals. Transition to GPS Wing, JC	REW,			
Title: Advanced Electronics Manufacturing - Large Affordable Substrates	S		0.825	0.500	0.000
Description: High performance infrared (IR) focal plane arrays (FPAs) at that are currently only available in relatively small wafer sizes. This effort (DoD) investments to enable a domestic source to manufacture larger Cassured availability of CZT substrates that will enable affordable, high period wide area search, long range ID, and dual band multispectral aided target move. Large, affordable CZT substrates from a domestic source will init infrared imaging systems (FLIR) Engine Engineering Manufacturing Devito space, strategic, and tactical systems.	t will leverage prior and concurrent Department of D ZT substrates. The results will be reduced cost and erformance ground and air IR sensor systems with re et detection capability against difficult targets while ially transition on FPAs for the 3rd Gen forward-look	Defense I rapid on-the- king			
FY 2012 Accomplishments: Design reviews of a furnace capable of handling larger boules were comefforts. Produced and tested 720p Focal Plane Arrays (FPAs). Matured domestic substrates into various IR programs including AIDE LRAS3 (ra one CdZnTe boule to produce substrates for downstream manufacturing	vertical gradient freeze boule growth. Incorporated pid prototype in-theater system). Cut and character	d			
FY 2013 Plans: Complete installation of the furnace for boule and substrate manufacturir size. Improve uniformity and reduce precipitates size in boule. Evaluate specification, such as parallelism, total thickness variation, chipping, scra Conduct a final demonstration of the product. Obtain a TRL6/MRL7 level Development and Demonstration build.	critical substrate factors that are part of the final su atches, etc. Initiate a Low Rate Production status.	bstrate			
Title: Advanced Electronics Manufacturing - Sensor Hardening			0.096	0.750	0.000
Description: The F-35 Joint Strike Fighter (JSF) has the requirement to accomplishment. Current F-35 Electro-Optical Targeting System (EOTS (EODAS) focal plane arrays (FPAs) suffer manufacturing yield and cost investments in laser protection technology to make manufacturing improinto the FPA's Read-Out Integrated Circuits (ROICs) while concurrently the total cost to F-35 to meet this requirement. The goal is to increase the Level to TRL/MRL 6 (demonstrate/produce prototype system or subsystem).	5) and Electro-Optical Distributed Aperture System issues. This effort will leverage prior and concurrer vements that incorporate laser protection technolog reducing ROIC defects (improving yield) and minim ne Transition Readiness Level/Manufacturing Read	nt DoD gy izing iness			

PE 0603680D8Z: Defense Wide Manufacturing Science and

UNCLASSIFIED

	UNCLASSIFIED					
Exhibit R-2A, RDT&E Project Justification: PB 2014 Office of Secreta	ary Of Defense		DATE:	April 2013		
APPROPRIATION/BUDGET ACTIVITY 0400: Research, Development, Test & Evaluation, Defense-Wide BA 3: Advanced Technology Development (ATD)	R-1 ITEM NOMENCLATURE PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program		DIECT D: Manufacturing Science and anology Program			
B. Accomplishments/Planned Programs (\$ in Millions)		FY	2012	FY 2013	FY 2014	
hardened FPAs in time for the F-35 Block 5 Upgrade. These technologi Wavelength Infrared detector, including those on tactical and reconnaiss		n				
FY 2012 Accomplishments: Continued Manufacturing Readiness Assessments (MRA) for both EOTS production scale-up effort which yielded multiple Grade A devices (hybridewars. Completed thermal cycle testing of an initial group of dewars. B Critical Design Review. Provided the ROIC design to the foundry. Deterrior limiters in dewars. Evaluated/identified numerous qualified alternative address FPA damage through enhancement of the ROIC detector, incorrup to increase manufacturability. Initiated system engineering studies or	dized ROICs). Began integration of FPA devices into egan life cycle testing. Completed a hardened ROIC mined the thermal modeling and placement concepts a foundries and ROIC designers. Continued efforts to prorating design changes simultaneously with wafer and the second sec	S O				
FY 2013 Plans: Conclude FPA production scale-up activities to achieve a TRL6/MRL6 le Hardened EODAS FPA. Conclude system engineering studies on target Initiate additional thermal cycle testing of dewars. Begin a second versic another MRA. Complete the ROIC fabrication. Finish the FPA build. Cor Force Base. Conduct transitional activities in preparation for the F-35 B	evel. Make available a Hardened EOTS FPA and a ting and warning systems. Continued life cycle testing on of the ROIC/detector hybridization effort. Conduct induct laser susceptibility testing at Wright Patterson					
Title: Advanced Electronics and Optics			0.626	5.255	10.640	
Description: Advanced Electronics is a series of efforts addressing advapplications such as sensors, radars, power generation, switches, and osignificant productivity and efficiency gains in the defense manufacturing delivery of technical capabilities to impact current warfighting operations acquisition time and risk of our major defense acquisition programs.	optics for defense applications. These efforts provide g base. These manufacturing technologies accelerate	te				
Tin Whisker Mitigation project: One significant issue is the need to move to produce lead-free solder create further issues such as the formation celectronics to short out. The Tin Whisker Mitigation project will demonst surfaces. The objective is to show significantly reduced or completely performance characteristics of the test components.	of unwanted tin whisker structures, which can cause trate controlled grain structure in soldered joints and	plated				
Silicon Carbide (SiC) High Efficiency Power Switches: Another emerging Silicon Carbide High Efficiency Power Switches to enable a new class of PE 0603680D87: Defense Wide Manufacturing Science and						

	UNCLASSIFIED					
Exhibit R-2A, RDT&E Project Justification: PB 2014 Office of Secreta	ry Of Defense		DATE:	April 2013		
APPROPRIATION/BUDGET ACTIVITY 0400: Research, Development, Test & Evaluation, Defense-Wide BA 3: Advanced Technology Development (ATD)	R-1 ITEM NOMENCLATURE PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program	P680	1),			
B. Accomplishments/Planned Programs (\$ in Millions)			FY 2012	FY 2013	FY 2014	
B. Accomplishments/Planned Programs (\$ in Millions) at higher voltages, higher frequencies, less volume / weight, higher tempand better power quality for Program Executive Office Ground Combat S Power Conversion Module. Mini Short Wave Infrared (SWIR) Cameras and ManTech for SWIR Imagare being developed that are smaller, use less power, have a lower cost improved functionality over sensors presently in use. These new SWIR target designation lasers during day and night, to identify friend or foe at Applications include several night vision and targeting system programs Manufacturability of Vertical Cavity Surface Emitting Lasers (VCSELs): Office development focuses on the manufacturability of VCSELs. This effort will technologies by reducing their operational cost, increasing their reliability without substantially increasing the processing and packaging requirement front-end with specialized in-house process steps, allowing more flexibility previously-invested capital. This project is expected to benefit numerous Anubis, Spectre-FINDER, Speckles, TigerMoth, WAAS, PAWS, IPODS, IDNST, TLDS, Big Safari, OEF, OIF, STINGER, and ARGUS. Future efforts will focus on advances in fuel cells, radars, conformal sense FY 2012 Accomplishments: Tin Whisker Mitigation project: Initiated mitigation manufacturing activitied demonstrate the elimination of tin whiskers. Fabricated and tested control	gers: Thermoelectric Cooler (TEC)-less SWIR image than currently available SWIR imagers, and offer imagers will be used by warfighters including SOF to long range at night, and to operate with covert lase with the Army, Navy, Air Force, and SOCOM. One emerging manufacturing technology undergoing all allow the enhanced use of high-power laser dioderly and yield, and improving their large array scalabilitients. Will apply a modern factory approach of a fability for DoD procurement cycles and leveraging instate programs, including: PUMA, RAVEN, TigerShark, AngelFire, MAV-OBAT, nLoss, LOS-short, CLRF, Jesors, and solder free electronics.	ers to see ty less illed,	FY 2012	FY 2013	FY 2014	
to test whisker propensity and perform other mechanical tests. Assessed surface plating, wave, Surface Mount Technology reflow, hot bar, and ha addressed: 1) reduction of internal stresses that cause tin whisker forma 3) crystal orientation and cross-sectional analysis of a variety of solder journing Surface Insulation Resistance testing with marginal levels of containing Surface Insulation Resistance testing with marginal levels of containing Surface Insulation Resistance testing with marginal levels of containing Surface Insulation Resistance testing with marginal levels of containing Surface Insulation Resistance testing with marginal levels of containing Surface Insulation Resistance testing with marginal levels of containing Surface Insulation Resistance testing with marginal levels of containing Surface Insulation Resistance testing with marginal levels of containing Surface Insulation Resistance testing with marginal levels of containing Surface Insulation Resistance testing with marginal levels of containing Surface Insulation Resistance testing with marginal levels of containing Surface Insulation Resistance testing With Marginal Insulation Resistance Insulatio	d the solder joint quality effect that treatments have and soldering processes with lead-free soldering. Ef tion; 2) strength of the solder joint to cause pad cra pints; and 4) improvement for electrochemical migra	on fort tering;				

Exhibit R-2A, RDT&E Project Justification: PB 2014 Office of Secreta	ry Of Defense		DATE: A	April 2013	
APPROPRIATION/BUDGET ACTIVITY 0400: Research, Development, Test & Evaluation, Defense-Wide BA 3: Advanced Technology Development (ATD)	R-1 ITEM NOMENCLATURE PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program	P680: /	OJECT 80: Manufacturing Science and hnology Program		nd
B. Accomplishments/Planned Programs (\$ in Millions)			FY 2012	FY 2013	FY 2014
SiC High Efficiency Power Switches. Focus on improvements in SiC star size to 6". Reduce substrate defects, including micropipe density, to imp 6" substrates.					
Mini SWIR Cameras and ManTech for SWIR Imagers: Develop robust yield. Improve backside processing costs.	4" wafer processes to reduce breakage and increas	е			
Manufacturability of VCSELs: Initiate hermetic design efforts, creating he by design" VCSEL chip process technology by processing direct passive operating life and shelf-life. Begin to standardize the package at the sub-of insertion to replace edge-emitting products in use by the marketplace arrays.	ation schemes directly onto the wafer to extend the -mount and heat-sink level. This is required for ease	.			
FY 2014 Plans: SiC High Efficiency Power Switches: Develop manufacturing technologic devices through enhanced material growth and high-yield device fabrica 6" substrates.					
Mini SWIR Cameras and ManTech for SWIR Imagers: Continue efforts to reduce costs. Improve hybridization yields and costs; develop a high through with automation of die bonding and wire bonding. Plan for sensor packat	roughput, self aligning process. Reduce packaging				
Manufacturability of VCSELs: Continuing hermetic design and standardic packaging alternatives for high-volume system insertion opportunities. D Pick-n-Place and Surface Mount Technology PCB-stuffing assembly line to remain consistent with wafer-scale packaging. Evaluate cooling technological techniques.	Develop low-cost wafer level packages compatible was, using multilayer ceramics and PCB technology	ith			
Title: Advanced Materials Manufacturing - Advanced Body Armor			0.913	1.250	0.00
Description: While current body armor is effective, it is too heavy for so reduction in system weight would significantly increase warfighter accep leverage prior DoD investments to mature three complimentary manufactory 10%-15% while improving ballistic performance and flexibility. Cost v	tance, mobility, agility, and endurance. This effort weturing technologies that will reduce body armor weigh	/ill ght			

PE 0603680D8Z: Defense Wide Manufacturing Science and

	UNCLASSIFIED				
Exhibit R-2A, RDT&E Project Justification: PB 2014 Office of Secreta	ry Of Defense		DATE:	April 2013	
APPROPRIATION/BUDGET ACTIVITY 0400: Research, Development, Test & Evaluation, Defense-Wide BA 3: Advanced Technology Development (ATD)	R-1 ITEM NOMENCLATURE PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program	P680: <i>Ma</i>	PROJECT P680: Manufacturing Science and Technology Program		
B. Accomplishments/Planned Programs (\$ in Millions)		F	Y 2012	FY 2013	FY 2014
by 10X-20X. The project will mature three manufacturing technologies for technologies in a laboratory to a capability to produce them in an environ technologies are: 1) Dissimilar Material Assembly Technology to integrate organic and inorganic constituents into a unified body armor system. 2) of time for the production of composite material enabling 10% lighter armor modification of ballistic ceramics and associated processes, which will in improve ballistic integrity and manage adverse shock events due to ballistic	nment representative of a production facility. The the te ceramic, polymer adhesives, composites, and otle Co-consolidation processing, to reduce cost and cylor while maintaining ballistic performance. 3) Multi-scaled new additive processes and metallic substrates.	ree ner cle cale			
FY 2012 Accomplishments: Successfully demonstrated novel backing architecture to reduce back far demonstrated on flat plate configurations using modified ceramic proces kind Dissimilar Materials Assembly System (DMAS) machine design con enables 20-40% reduction in touch labor associated with complicated as	ses and ceramic powder compositions. First-of-its- nplete. Built, installed, and operational. DMAS dire	ectly			
FY 2013 Plans: Technology down-select initiated (including composite, ceramic, adhesiv lighter (5.5 pounds for size medium) ESAPI side plate. Conduct interlay parameters and complete ballistic and related testing. Process down se	er materials bonding and assembly. Develop evalu	ation			
Title: Advanced Materials Manufacturing - Field Assisted Sintering Tech	nology (FAST)		0.500	0.450	0.000
Description: This effort addresses limitations of conventional sintering p days in a sintering oven, and the beneficial characteristics of nano-struct FAST has the potential to dramatically reduce cycle time and manufactu of nano-structured materials. The FAST process passes a pulsed direct the combination of rapid heating and compressive loading results in fine that are not possible with conventional sintering processes. Many parts candidates for FAST, but this project will focus on ceramic body and veh windows, heat sinks for electromagnetic propulsion cooling, and hyperso propulsion.	tured materials are lost when the material is sintere ring costs while maintaining the beneficial characte current through the part while it is pressed in a die grained, fully dense materials in short processing that are made with a powder press and sinter procesticle armor, tungsten kinetic energy penetrators, infragramments.	d. ristics and mes ess are ared			
FY 2012 Accomplishments: Fabricated explosively formed penetrators and components, ballistic tiles process in fabricating ceramic matrix composite components with fiber's	·	-			

PE 0603680D8Z: Defense Wide Manufacturing Science and

	UNCLASSIFIED			
Exhibit R-2A, RDT&E Project Justification: PB 2014 Office of Secreta	ry Of Defense	DATE:	April 2013	
APPROPRIATION/BUDGET ACTIVITY 0400: Research, Development, Test & Evaluation, Defense-Wide BA 3: Advanced Technology Development (ATD)	R-1 ITEM NOMENCLATURE PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program	PROJECT P680: Manufacturion Technology Progra		nd
B. Accomplishments/Planned Programs (\$ in Millions)		FY 2012	FY 2013	FY 2014
experimentally the benefit of WC (Tungsten Carbide) additives for minim (Tungsten). Began sintering study on WC-12%Co. Designed molds for				
FY 2013 Plans: Extend Area Protection & Survivability Warhead Testing. Fabrication of testing of automation, optimization of automation system, document productions.		,		
Title: Enterprise and Emerging Processes - Rapid Manufacturing of Aero	ospace Structures	0.516	0.000	0.000
Description: There is a strong need to fabricate timely and affordable as rapid fielding of materials and systems to serve the defense manufacturing from additive manufacturing is one in which there are multiple, complex, within an inlet duct. This program involves design, fabrication, testing as manufacturing. Complex designs such as conformal lattice structures, we for small remotely piloted aircraft, but may only be successfully manufacturing.	ng base. An example of a system that could benefit embedded systems, such as air flow control actuato ad performance analysis of various parts using additi ith high strength and low mass, are highly advantag	ve eous		
FY 2012 Accomplishments: Used conformal lattice software developed to optimize lightweight confor Aircraft (RPA). Completed mechanical analysis of nanomodified polyme Completed thermal control upgrades for greater thermal uniformity and not conformal lattice structure approach (wings, tail, fuselage, nosecone). Continuitiated. Manufactured inlet duct actuator inserts with integrated power techniques. Manufactured various PRT designs and air flow testing was tooling using a washout mandrel additive manufacturing. Test the full conmanufacturing tool with active flow control inserts also manufactured using techniques. Complete flight test for the conformal lattice structure RPA,	ric parts and microwave post processing densification naterial densification. Designed small RPA using ost comparison to carbon fiber composite structure ed resonance tubes (PRTs) using additive manufact compared to the theoretical values. Built composite mposite inlet duct built on the polymeric additive ng one of the two polymeric additive manufacturing	uring		
Title: Advanced Materials Manufacturing		4.524	6.311	8.680
Description: Advanced Materials Manufacturing is a series of efforts adrange of materials such as composites, metals, ceramics, nanomaterials provide significant productivity and efficiency gains in the defense manufaccelerate delivery of technical capabilities to impact current warfighting cost, acquisition time and risk of our major defense acquisition programs	, metamaterials, and low observables. These efforts facturing base. These manufacturing technologies wo operations, and manufacturing technologies to reduce the control of	will ill		

	UNULASSII ILD				
Exhibit R-2A, RDT&E Project Justification: PB 2014 Office of Secreta	ary Of Defense		DATE:	April 2013	
APPROPRIATION/BUDGET ACTIVITY 0400: Research, Development, Test & Evaluation, Defense-Wide BA 3: Advanced Technology Development (ATD)	R-1 ITEM NOMENCLATURE PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program			ng Science al m	nd
B. Accomplishments/Planned Programs (\$ in Millions)		F	Y 2012	FY 2013	FY 2014
Advanced materials manufacturing technologies undergoing developme for rapid fabrication of structural components.	ent include materials for ballistic survivability and ma	terials			
Cast Eglin Steel: An effort is underway to establish Cast Eglin steel cher maximum protection and effectiveness for Hard and Deeply Buried Targ for the single piece cast underbody protection system, and bomb bodies to meet geometric and blast requirements.	get (HDBT) targets. Will create a primary casting pro				
Cold Spray Deposition: The objective for Cold Spray Deposition is to cremanufacturer applied corrosion/wear prevention treatment for magnesiu Inability to repair is causing significant readiness, sustainment, and safe Working with the original equipment manufacturer to transition the process and overhaul condemned gearboxes in storage.	um gearbox housings and parts on numerous platfor ety issues (20% of the fleet is affected at any given ti	ms. me).			
Net-Shaped Field Assisted Sintering Technology (FAST): FAST will set production of two ultra high temperature materials components that requitate are not achievable via other processes. This technology addresses (flute shaped) made from W (Tungsten) and TaC alloys and sharp leading ceramics. This effort will mature the manufacturing readiness of convenience delivery times.	uire full density materials with nano tailored microstr s near net shaped, thin walled axial rocket nozzle ins ng edges with attachment features made from Hf-ba	serts ised			
Fastener Fill: The F-35 Fastener Fill project will address the challenges which can take as long as 2 minutes per fastener and provides no indica 40,000 fasteners per aircraft for F-35, this is a significant manufacturing skived to meet flushness requirements. The project objective is to refine System which is an automated combination melt, compress, and skive to 15 seconds per fastener.	ation of installation quality other than feel. With over issue. In addition, excess materials must be manual the contractor's prototype Rapid Intelligent Fastene	ally er Fill			
Automated and Rapid Boot Installation Process: This process will reduce which are not suitable for full-rate production and represent 40% of the chas identified the following areas to be targeted: (1) automation of the had	cost in component finishing. A risk assessment anal				

Exhibit R-2A, RDT&E Project Justification: PB 2014 Office of Secreta	ary Of Defense	,	DATE:	April 2013	
APPROPRIATION/BUDGET ACTIVITY 0400: Research, Development, Test & Evaluation, Defense-Wide BA 3: Advanced Technology Development (ATD)	R-1 ITEM NOMENCLATURE PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program			ng Science ai m	nd
B. Accomplishments/Planned Programs (\$ in Millions)			FY 2012	FY 2013	FY 2014
automation of additional trimming, bonding, and pasting activities curren skill/training; and (4) reduction of the waste incurred in cutting/darting bo		nnician			
FY 2012 Accomplishments: Cast Eglin Steel: Request for Proposal, conducted contract award evalu	ation, and awarded contract.				
Cold Spray: Project Kickoff June 5, 2012. Created a proven repair proce the original equipment manufacturer applied corrosion/wear prevention to platforms. Inability to repair was causing significant readiness, sustainment	treatment for magnesium gearbox housings on num				
Net-Shaped Field Assisted Sintering (FAST): The near net shape densif composite powders. Two different vertical die designs were developed a The preliminary results showed that the near net shape consolidation by microstructures.	and tested to produce a near net shape, nozzle thro	at.			
Fastener Fill: Released Request for Proposal, conducted contract award	d evaluation, and awarded contract.				
Automated and Rapid Boot Installation: Released Request for Proposal, contract.	, conducted contract award evaluation, and awarded	d			
FY 2013 Plans: Cast Eglin Steel: Establish Eglin steel chemistry specifications to maxim maximum effectiveness for hard and deeply buried targets. Create a pri protection system, and bomb bodies. Employ an integrated computation casting process to mitigate potential processing problems.	imary casting process for the single piece cast unde	erbody			
Cold Spray: Work with the original equipment manufacturer to transition repair, and overhaul condemned gearboxes in storage. Process validation		aintain,			
Net-shaped FAST: Complete high temperature bend strength with grain for the carbide dispersoid and conduct a more detailed processing study material to conduce a detailed thermal-mechanical behavior analysis. Details of the conduct of the carbide strength with grain for the carbide dispersoid and conduct a more detailed processing study material to conduce a detailed thermal-mechanical behavior analysis.	y. Fabricate a large billet in the large FAST unit for ϵ	enough			

Exhibit R-2A, RDT&E Project Justification: PB 2014 Office of Secreta	ry Of Defense		DATE: A	April 2013	
APPROPRIATION/BUDGET ACTIVITY 0400: Research, Development, Test & Evaluation, Defense-Wide BA 3: Advanced Technology Development (ATD)	R-1 ITEM NOMENCLATURE PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program		ECT Manufacturin ology Progran		nd
B. Accomplishments/Planned Programs (\$ in Millions)			FY 2012	FY 2013	FY 2014
morphology, mechanical and thermal properties and Non-Destructive Evup to near net shape nozzle and segmented leading edge.	valuation results. Start fabrication of prototype and s	scale-			
Fastener Fill: Develop automation plan and integrate into robotic arm. Mapplications to include hard to reach areas such as inlet ducts and QC viskived per requirements.	• •	nd			
Automated and Rapid Boot Installation:. Automated boot kit development development.	nt and pressure sensitive adhesive application				
FY 2014 Plans: Cast Eglin Steel: Validate cast process that ensures cast in pockets, slop requirements that also facilitate ease of next higher level assembly. Eglin scale demonstrations.					
Cold Spray: Original equipment manufacturer demonstration & qualificat analysis and engineering validations are scheduled.	tion of the UH-60 Sump Housing. System prove-out				
Net-shaped FAST: Complete validation and durability testing then proced demonstration. The team will document process efficiency, and then ide to industry.		sition			
Fastener Fill: Installation at Northrop Grumman Palmdale F-35 inlet duct includes first article acceptance.	t manufacturing line and qualification and testing wh	ich			
Automated and Rapid Boot Installation: Single piece injection molding applications development which will include scanning & compens to coincide with manufacturing development.					
Title: Enterprise and Emerging Manufacturing			4.257	1.575	2.721
Description: Enterprise and Emerging Manufacturing is a series of effor and enterprise business practices for defense applications. Key focus a advanced manufacturing enterprise, machining, robotics, assembly, and	reas include direct digital (or additive) manufacturing				

PE 0603680D8Z: Defense Wide Manufacturing Science and

	UNCLASSIFIED				
Exhibit R-2A, RDT&E Project Justification: PB 2014 Office of Secreta	ry Of Defense	,	DATE:	April 2013	
APPROPRIATION/BUDGET ACTIVITY 0400: Research, Development, Test & Evaluation, Defense-Wide BA 3: Advanced Technology Development (ATD)	R-1 ITEM NOMENCLATURE PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program			ng Science a am	nd
B. Accomplishments/Planned Programs (\$ in Millions)			FY 2012	FY 2013	FY 2014
enterprise business practices will accelerate delivery of technical capabi manufacturing technologies to reduce the cost, acquisition time and risk. With our adversaries forced to innovate rapidly to survive, it's become in own agility and flexibility. The focus is to find a solution to overcome a broost, time, security, and storage space. Through the use of secure satell access CAD designs for replacement parts, allowing them to repair equipments. It allows operators to modify a part's design based on its performance of applications, and methods for exchange of 3D official technologies undergoing development include:	of our major defense acquisition programs. Icreasingly important for the U.S. military to improve urdensome acquisition cycle requiring a great amoulite data links or a local parts database, warfighters pment without the need to establish supply chains operformance in the field. Large-scale, challenge for advanced, interoperable	int of can or wait e			
National Additive Manufacturing Innovation Institute (NAMII): Collaborati parts directly from digital data such as 3D Computer-aided design (CAD) designers, allowing the use of very complicated geometries. It is as econthousands and thus undermines economies of scale. Using additive mar in the field and enable deployed units to remain mission-ready. Through database, warfighters near deployment locations could access CAD desequipment without the need to establish supply chains or wait for shipmed based on its performance in the field. There is a strong need to fabricate production environment for rapid fielding of materials and systems. An econtrol actuator within an inlet duct. This program involves design, fabric using additive manufacturing. Complex designs, such as conformal latticusing methods such as additive manufacturing.	drawings. It provides almost limitless freedom to nomical to produce single items as it is to produce nufacturing would allow for rapid replacement of panthe use of secure satellite data links or a local partigns for replacement parts, allowing them to repair ents. It would allow operators to modify a part's desertimely and affordable aerospace structures in a example of a system that could benefit is an air flow cation, testing and performance analysis of various	rts ts ign , parts			
MTConnect Challenge: The MTConnect Challenge focuses on developin MTConnect interoperable protocol, for use on machining platform developing that provides the capability to pass data from machine tools to higher levi standard.	opment. MTConnect is an open communication star	ndard			
Framework for Assessing Cost and Technology (FACT): Producibility an performance, manufacturing processing techniques and cost can be sim		ign			

PE 0603680D8Z: Defense Wide Manufacturing Science and Technology ...

	UNCLASSIFIED				
Exhibit R-2A, RDT&E Project Justification: PB 2014 Office of Secreta	ary Of Defense		DATE:	April 2013	
APPROPRIATION/BUDGET ACTIVITY 0400: Research, Development, Test & Evaluation, Defense-Wide BA 3: Advanced Technology Development (ATD)	R-1 ITEM NOMENCLATURE PE 0603680D8Z: Defense Wide Manufacturing Science and Technology Program			ng Science a ım	nd
B. Accomplishments/Planned Programs (\$ in Millions)			FY 2012	FY 2013	FY 2014
solution. Current producibility analysis tools do not reuse and connect es Sustainment and Maintenance will be impacted by maturing advanced sustainment costs associated with spare parts acquisition and weapons selection of a manufacturing process to minimize cost given the estimate using FACT will be critical for performing analyses associated with integrating highlight the manufacturing and lifecycle costs associated with the necess operational requirements.	sustainability analyses operating within FACT to red system maintenance. The technology will enable co ed spare part lot sizes. Block Upgrades or Recapita grating new requirements into an existing platform to	orrect llization			
FY 2012 Accomplishments: MT Connect Challenge: Launched a shop floor application (including ma and stimulate a broader base of software and system architects, to developlications based on extensions to the MTConnect standard to enable infrastructure for the defense enterprise. Began an effort to create valual manufacturing, especially the lower tier producers, to enhance their man management goals. Established subcontractors contract agreements.	elop advanced enterprise, facility, and machine cont a more efficient and competitive domestic manufac able tools and applications that can be easily adopte	trol turing ed by			
NAMII: Developed a national roadmap for additive manufacturing in met improve additive manufacturing methods for DoD weapons systems.	tals, electronics, and polymers. Launched initial pro	jects to			
FY 2013 Plans: MTConnect Challenge: Study the incorporation of in situ metrology, proto measure/improve part quality and system performance. Execute conceprocess reliability, and yield. Research materials, part, and component of property relationships to maximize potential effectiveness. Enable the rathrough integration of digital product designs and manufacturing capability.	cepts to improve build rates, manufacturing through characterization to better understand structure/proceapid design and fabrication of current and future plate	put, ess/			
Framework for Assessing Cost and Technology (FACT): Identify, solicit, Reduce the time required to perform tradeoff analyses for new system p Vehicle). This will improve the integrated nature of the components, reducostly.	production planning (such as for the Amphibious Co	mbat			
FY 2014 Plans: MTConnect Challenge: Review submissions for accuracy, credibility, effective evaluation and assessment of the competing offerings, determine the wi		n			

PE 0603680D8Z: Defense Wide Manufacturing Science and Technology

Technology ...
Office of Secretary Of Defense

R-1 Line #47

ON	CLASSIFIED					
Exhibit R-2A, RDT&E Project Justification: PB 2014 Office of Secretary Of D	efense			DATE: A	April 2013	
APPROPRIATION/BUDGET ACTIVITY 0400: Research, Development, Test & Evaluation, Defense-Wide BA 3: Advanced Technology Development (ATD)	R-1 ITEM NOMENCLATURE PE 0603680D8Z: Defense Wide Manufacturing Science and Techr Program		PROJECT P680: Ma Technolog	nufacturin	g Science an n	d
B. Accomplishments/Planned Programs (\$ in Millions)			F	/ 2012	FY 2013	FY 2014
Framework for Assessing Cost and Technology (FACT): Evaluate and model of for insertion to a PLM-to-PLM information data exchange format. It is anticipate specifications to accommodate welding and machining processes will begin for M777 spare parts project to be realized starting in the 3Q-FY15.	ed that benefits associated with upo	lating desigr	n			
Title: Advanced Manufacturing Innovation Institutes				0.000	0.000	12.000
Description: Technical innovation and leadership in manufacturing are essenting prosperity to enable our military to maintain technological advantage and global Manufacturing Innovation (IMI) will serve as regional hubs to accelerate technological advantage and global Manufacturing Innovation (IMI) will serve as regional hubs to accelerate technological accelerate technological advantage and production processes were execution and funding by the Departments of Defense (DoD), Energy (DoE), and Science Foundation (NSF) to support the establishment of the IMIs will spur included the production of the IMIs will meet critical government and Warfighter needs. The concept of these of Advisors on Science and Technology (PCAST) report titled "Capturing Dome Manufacturing," published in July 2012.	Il dominance. To support these goal logical innovation into commercial via shared public-private sectors. and Commerce (DoC), NASA, and the dustry cost-share for manufacturing on among government, industry, ar institutes is highlighted in the Presi	als, Institutes application a Collaboration ne National innovation nd academia dent's Cour	and /e and			
FY 2014 Plans: Establish two Advanced Manufacturing Innovation Institutes to address Intellige Electronics Manufacturing Innovation.	ent Design and Manufacturing (IDM	1) and III-V (Opto-			
	Accomplishments/Planned Prog	grams Subt	otals	19.026	21.966	34.041
		FY 2012	FY 2013			
Congressional Add: Industrial Base Innovation Fund		30.000	-			
FY 2012 Accomplishments: Program investments were executed in manufacturing turgent operational needs; expanded domestic manufacturing capacity; and addition or reliance on foreign sources for certain defense products. The IB defense-wide manufacturing science and technology issues, with the additional surge and/or diminishing material source issues. In addition, these programs a with implementation on a current platform or one undergoing acquisition targets.	dressed concerns over limited BIF programs all addressed key I requirements of addressing Ill had a clear transition path					

PE 0603680D8Z: Defense Wide Manufacturing Science and

APPROPRIATION/BUDGET ACTIVITY D400: Research, Development, Test & Evaluation, Defense-Wide BA 3: Advanced Technology Development (ATD) Project completion. The following areas of investment were executed to enable a diverse suite of advanced manufacturing production improvements: - Connecting American Manufacturing – created a national-level, integrated framework to enable rapid, high-density, multi-sector brokering between buyers and US suppliers - Additive manufacturing initiative – created a large collaboration on additive manufacturing, which enabled innovative research, transition to multiple DoD platforms, and educational opportunities - Non-Destructive Evaluation (NDE) for Electron Beam additive manufacturing – developed rapid and affordabl NDE techniques for Ti and other metal parts manufactured using a directed energy additive technique - Read-out Integrated Circuit for Electro-optical distributed aperture system (EODAS) – redesigned, fabricated, tested, and laser hardened EODAS ROIC to use state-of-the-art foundry equipment and increase yield Slurry Dip Automation – developed an automated dipping and slurry management system for flare	FY 2012	Technolog	DATE: April 2013
PE 0603680D8Z: Defense Wide A 3: Advanced Technology Development (ATD) project completion. The following areas of investment were executed to enable a diverse suite of advanced manufacturing production improvements: - Connecting American Manufacturing – created a national-level, integrated framework to enable rapid, high-density, multi-sector brokering between buyers and US suppliers - Additive manufacturing initiative – created a large collaboration on additive manufacturing, which enabled innovative research, transition to multiple DoD platforms, and educational opportunities - Non-Destructive Evaluation (NDE) for Electron Beam additive manufacturing – developed rapid and affordabled NDE techniques for Ti and other metal parts manufactured using a directed energy additive technique - Read-out Integrated Circuit for Electro-optical distributed aperture system (EODAS) – redesigned, fabricated, tested, and laser hardened EODAS ROIC to use state-of-the-art foundry equipment and increase yield.	FY 2012	P680: Mar Technolog	nufacturing Science and
manufacturing production improvements: - Connecting American Manufacturing – created a national-level, integrated framework to enable rapid, high-density, multi-sector brokering between buyers and US suppliers - Additive manufacturing initiative – created a large collaboration on additive manufacturing, which enabled innovative research, transition to multiple DoD platforms, and educational opportunities - Non-Destructive Evaluation (NDE) for Electron Beam additive manufacturing – developed rapid and affordabl NDE techniques for Ti and other metal parts manufactured using a directed energy additive technique - Read-out Integrated Circuit for Electro-optical distributed aperture system (EODAS) – redesigned, fabricated, tested, and laser hardened EODAS ROIC to use state-of-the-art foundry equipment and increase yield.		FY 2013	
manufacturing production improvements: - Connecting American Manufacturing – created a national-level, integrated framework to enable rapid, high-density, multi-sector brokering between buyers and US suppliers - Additive manufacturing initiative – created a large collaboration on additive manufacturing, which enabled innovative research, transition to multiple DoD platforms, and educational opportunities - Non-Destructive Evaluation (NDE) for Electron Beam additive manufacturing – developed rapid and affordabl NDE techniques for Ti and other metal parts manufactured using a directed energy additive technique - Read-out Integrated Circuit for Electro-optical distributed aperture system (EODAS) – redesigned, fabricated, tested, and laser hardened EODAS ROIC to use state-of-the-art foundry equipment and increase yield.			
density, multi-sector brokering between buyers and US suppliers Additive manufacturing initiative – created a large collaboration on additive manufacturing, which enabled innovative research, transition to multiple DoD platforms, and educational opportunities Non-Destructive Evaluation (NDE) for Electron Beam additive manufacturing – developed rapid and affordable NDE techniques for Ti and other metal parts manufactured using a directed energy additive technique Read-out Integrated Circuit for Electro-optical distributed aperture system (EODAS) – redesigned, fabricated, ested, and laser hardened EODAS ROIC to use state-of-the-art foundry equipment and increase yield.			
countermeasure products that effectively eliminated human operators from the dangerous process - On-tool Inspection of Fiber Placement – developed non-destructive evaluation and quality inspection techniques within the fiber placement head for in-process, rapid inspection, improving yield and process contrectured transparent armor – developed manufacturing technology of transparent armor, which enabled curved and thinner transparent structures and decreasing cost - Transparent Ceramics – Sapphire – created an approach to determine the significant factors affecting the velocity of single crystal growth of large sheet sapphire production Quallion Lithium-ion 6T Vehicle Starter Battery – Developed a lithium-ion military vehicle starter battery that significantly improves power and energy density of the standard 6T lead acid battery. Implemented semi-automated manufacturing processes to move this key component into high volume production and utilize Quallion Zero-Volt cells to reduce life cycle costs Saft Lithium Ion Energy Storage – Developed lithium ion electrochemical solution integrated with appropriate packaging and systems engineering that provides a Starting / Lighting / Ignition battery for military 14 Volt systems. This program will prime the pump of domestic lithium battery manufacture in large volumes Multi Function Periscope – specified goals and requirements, and began design work to develop a periscope for armored vehicles that merges an external view with sensor and vehicle health data. Multiple users benefitted from these programs including Air Force/Navy F-35 users, Army/Air Force flare users and Special Operations Command. Congressional Adds Subtots		0.000	

Exhibit R-2A, RDT&E Project Justification: PB 2014 Office of Secretary Of Defense

R-1 ITEM NOMENCLATURE PROJECT

0400: Research, Development, Test & Evaluation, Defense-Wide PE 0603680D8Z: Defense Wide

Manufacturing Science and Technology

P680: Manufacturing Science and Technology Program

Program

C. Other Program Funding Summary (\$ in Millions)

BA 3: Advanced Technology Development (ATD)

FY 2014 FY 2014 FY 2014

<u>:014</u>

Cost To

DATE: April 2013

<u>Line Item</u> <u>FY 2012</u> <u>FY 2013</u> <u>Base</u> <u>OCO</u> <u>Total</u> <u>FY 2015</u> <u>FY 2016</u> <u>FY 2017</u> <u>FY 2018</u> <u>Complete</u> <u>Total Cost</u>

• (BA3) 0603680F: Air Force

ManTech

(BA7) 0708045A: Army ManTech
(BA7) 0708011N: Navy ManTech
(BA7) 0708011S: DLA ManTech

APPROPRIATION/BUDGET ACTIVITY

Remarks

D. Acquisition Strategy

Not applicable for this item. Outyear data for "Other Program Funding" is contained within the Service budgets.

E. Performance Metrics

The majority of project performance metrics are specific to each effort and include measures identified in the project plans. The metrics include items such as target dates from project work break down schedules, production measures, production goals, production numbers and demonstration goals and dates. In addition, generic performance metrics applicable to the Defense-Wide Manufacturing, Science and Technology (DMS&T) program includes attainment of previous administration goal, "Speed technology transition focused on warfighting needs". The metrics for this objective and the objective of DMS&T is to transition 30% of completing demonstrations program per year. Due to the relatively new time frame of the DMS&T program, transition rates for completed efforts for this new project are not available yet.

UNCLASSIFIED

PE 0603680D8Z: Defense Wide Manufacturing Science and Technology ...